NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.002
   BODY: SEMICONDUCTOR MOLDING EPOXY. CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 250 TO 300 MICRON (6.25 TO 7.6 Micron) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRON (1.0 TO 2.0 Micron) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12 TO 1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076 mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25 mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

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